

# Product / Process Change Notification



N° 2016-063-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

## Introduction of Infineon Kulim, Malaysia as an additional wafer test location affecting dedicated products

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **01. February 2017**.
- Infineon aligns with the widely-recognized JEDEC STANDARD “**JESD46**“, which stipulates:  
“**Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.**”

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG  
Postal Address Headquarters: Am Campeon 1-12, D-85579 Neubiberg, Phone +49 (0)89 234-0  
Chairman of the Supervisory Board: Wolfgang Mayrhuber  
Management Board: Dr. Reinhard Ploss (CEO), Dominik Asam, Dr. Helmut Gassel, Jochen Hanebeck  
Registered Office: Neubiberg Commercial Register  
Amtsgericht München HRB 126492

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## ► Products affected:

Sales Name	SP N°	OPN	Package
CHIP S4921-5U	SP000013686	CHIPS49215UX1SA1	
TLE4921-5U	SP000013593	TLE49215UHALA1	PG-SSO-4
TLE4921M5U	SP000098770	TLE4921M5UHALA1	PG-SSO-4

## ► Detailed Change Information:

**Subject:** Introduction of Infineon Kulim, Malaysia as an additional wafer test location affecting dedicated products.

**Reason:** To continuously ensure the delivery capability to our customers, the wafer test capacity will be extended.

Description:	<u>Old</u>	<u>New</u>
Wafer test location:	■ Infineon Villach, Austria	■ Infineon Villach, Austria  <i>or</i> ■ Infineon Kulim, Malaysia

► **Product Identification:** Traceability is ensured by lot number.

► **Impact of Change:** No change in form fit or function and no impact on quality and reliability of the final product.  
The wafer test location verification is performed via the Advanced Measurement System Analysis (AMSA) methodology.

► **Attachments:** None

## ► Time Schedule:

- Final qualification report: AMSA assessment is available on demand
- First samples available: No samples planned due to no change of product.
- Intended start of delivery: April 2017

If you have any questions, please do not hesitate to contact your local Sales office.